

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP6060AGU uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS}(\text{ON})}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

V_{DS} =60V,I_D =60A

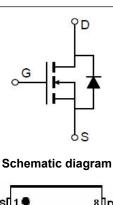
 $R_{DS(ON)} < 6.0 m\Omega$ @ $V_{GS} = 10V$ (Typ:5.3m Ω) $R_{DS(ON)} < 7.8 m\Omega$ @ $V_{GS} = 4.5V$ (Typ:6.5 m Ω)

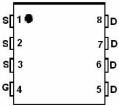
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

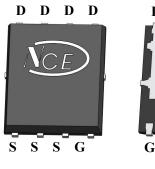
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

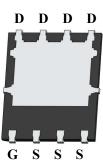
100% UIS TESTED! 100% ΔVds TESTED!





Marking and pin assignment





Top View

Bottom View

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|-----------------------|-------------|----------------|-----------|------------|----------|
| NCEP6060AGU | NCEP6060AGU | DFN5X6-8L | - | - | - |

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|-----------------------|------------|--------------|
| Drain-Source Voltage | V _{DS} | 60 | V |
| Gate-Source Voltage | Vgs | ±20 | V |
| Drain Current-Continuous (Silicon Limited) | I _D | 60 | Α |
| Drain Current-Continuous(T _C =100 ℃) | I _D (100℃) | 42.4 | Α |
| Pulsed Drain Current | I _{DM} | 240 | А |
| Maximum Power Dissipation | P _D | 70 | W |
| Derating factor | | 0.56 | W/℃ |
| Single pulse avalanche energy (Note 5) | Eas | 300 | mJ |
| Operating Junction and Storage Temperature Range | T_{J}, T_{STG} | -55 To 150 | $^{\circ}$ C |

NCEP6060AGU

Thermal Characteristic

| Thermal Resistance,Junction-to-Case ^(Note 2) | R _{eJC} | 1.78 | °C/W |
|--|------------------|------|------|
| Thermal Resistance,Junction-to-Ambient ^(Note 2) | R _{0JA} | 55 | °C/W |

Electrical Characteristics (T_C=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------|---------------------|--|-----|------|------|---------------|
| Off Characteristics | | | | ' | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250µA | 60 | | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =60V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | Igss | V _{GS} =±20V,V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS}=V_{GS},I_{D}=250\mu A$ | 1.2 | 1.8 | 2.5 | V |
| Danie Common On Otata Danietana | | V _{GS} =10V, I _D =20A | - | 5.3 | 6.0 | V µA nA |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =4.5V, I _D =20A | - | 6.5 | 7.8 | mΩ |
| Forward Transconductance | g FS | V _{DS} =10V,I _D =20A | 35 | - | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{lss} | \/ 20\/\/ 0\/ | - | 2100 | - | PF |
| Output Capacitance | Coss | V_{DS} =30V, V_{GS} =0V, | - | 359 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.0MHz - 12 | - | PF | | |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | - | 9 | - | nS |
| Turn-on Rise Time | t _r | V_{DD} =30 V , I_D =20 A | - | 3 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | $V_{GS}\text{=}10V,R_{G}\text{=}4.7\Omega$ | - | 31 | - | nS |
| Turn-Off Fall Time | t _f | | - | 5 | - | nS |
| Total Gate Charge | Qg | V 00V/1 00A | - | 36.6 | | nC |
| Gate-Source Charge | Q _{gs} | V_{DS} =30V, I_{D} =20A, | - | 6.7 | | nC |
| Gate-Drain Charge | Q _{gd} | V _{GS} =10V | - | 5.8 | | nC |
| Drain-Source Diode Characteristics | , | | • | | | 1 |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V,I _S =20A | - | | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | - | - | 60 | Α |
| Reverse Recovery Time | t _{rr} | T _J = 25°C, I _F = I _S | - | 40 | | nS |
| Reverse Recovery Charge | Qrr | $di/dt = 100A/\mu s^{(Note3)}$ | - | 50 | | nC |

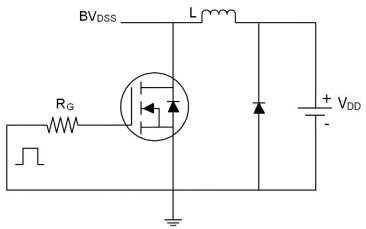
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=30V,V_G=10V,L=0.5mH,Rg=25 Ω

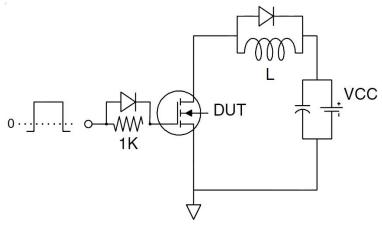


Test Circuit

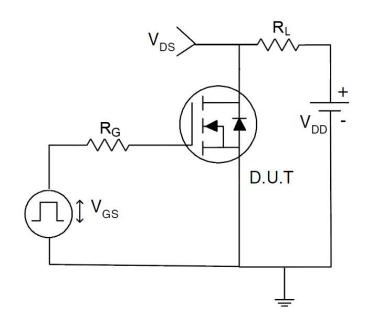
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics

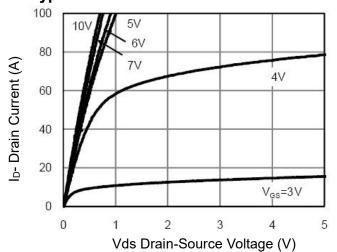


Figure 1 Output Characteristics

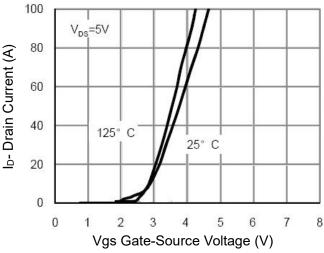


Figure 2 Transfer Characteristics

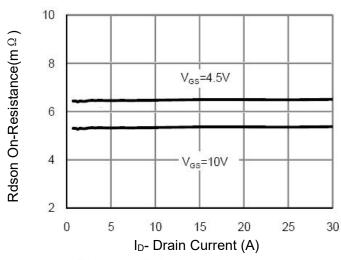


Figure 3 Rdson-Drain Current

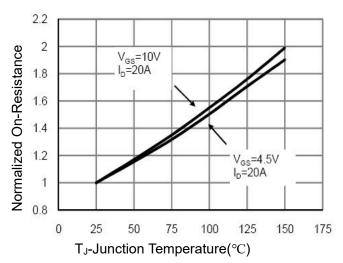


Figure 4 Rdson-JunctionTemperature

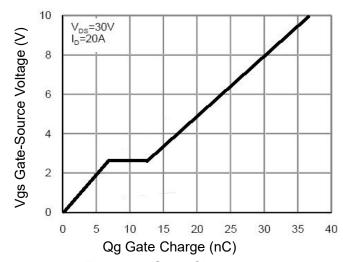


Figure 5 Gate Charge

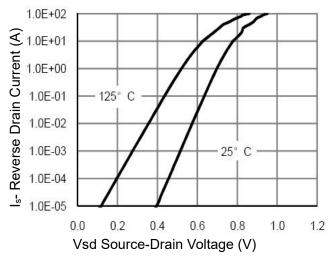


Figure 6 Source- Drain Diode Forward



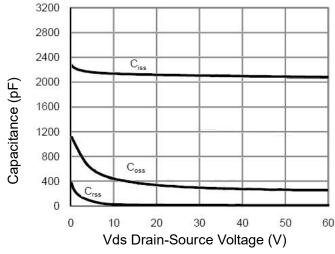


Figure 7 Capacitance vs Vds

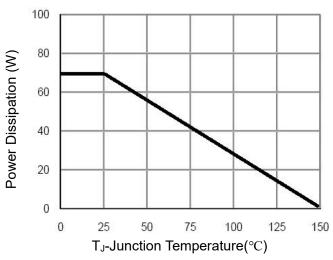


Figure 9 Power De-rating

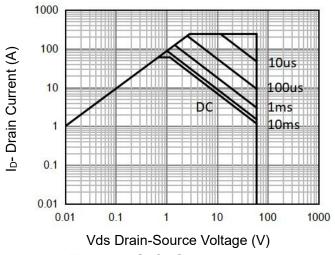


Figure 8 Safe Operation Area

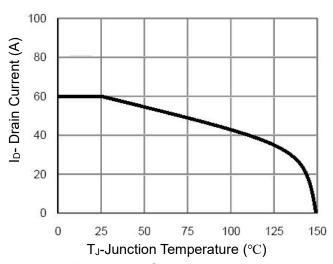


Figure 10 Current De-rating

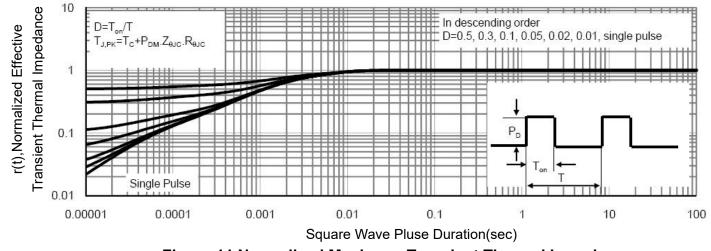
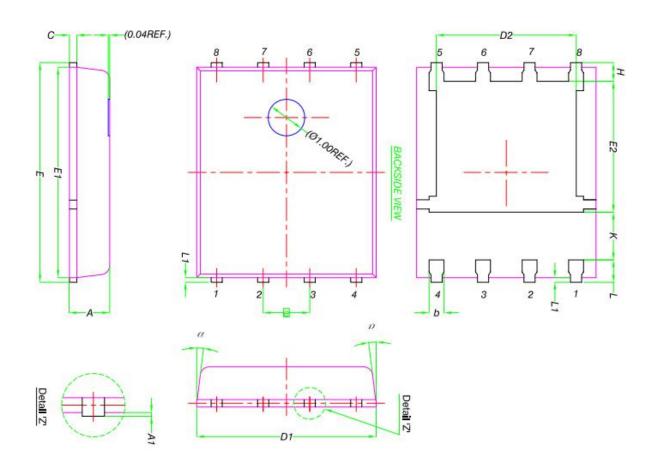


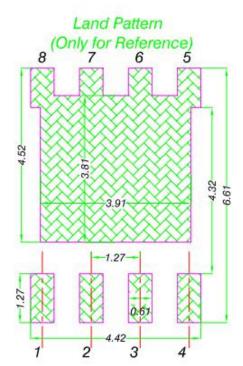
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



| | MILLIMETERS | | | |
|------|-------------|----------|------|--|
| DIM. | MIN. | NOM. | MAX. | |
| Α | 0.90 | 1.00 | 1.10 | |
| A1 | 0 | - | 0.05 | |
| b | 0.33 | 0.41 | 0.51 | |
| С | 0.20 | 0.25 | 0.30 | |
| D1 | 4.80 | 4.90 | 5.00 | |
| D2 | 3.61 | 3.81 | 3.96 | |
| Ε | 5.90 | 6.00 | 6.10 | |
| E1 | 5.70 | 5.75 | 5.80 | |
| E2 | 3.38 | 3.58 | 3.78 | |
| е | | 1.27 BSC | | |
| Н | 0.41 | 0.51 | 0.61 | |
| K | 1.10 | - | - | |
| L | 0.51 | 0.61 | 0.71 | |
| L1 | 0.06 | 0.13 | 0.20 | |
| α | 0° | 15 | 12° | |



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NCEP6060AGU

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